

E1SDA12-25.000M TR

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REGULATORY COMPLIANCE (Data Sheet downloaded on Sep 2, 2020)


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ITEM DESCRIPTION

Quartz Crystal Resonator HC49/UP Short 2 Pad Surface Mount (SMD) 3.2mm Height Metal Resistance Weld Seal 25.000MHz ± 30 ppm at 25°C, ± 50 ppm over 0°C to +70°C 12pF Parallel Resonant

ELECTRICAL SPECIFICATIONS

| | |
|-------------------------------|--|
| Nominal Frequency | 25.000MHz |
| Frequency Tolerance/Stability | ± 30 ppm at 25°C, ± 50 ppm over 0°C to +70°C |
| Aging at 25°C | ± 5 ppm/year Maximum |
| Load Capacitance | 12pF Parallel Resonant |
| Shunt Capacitance | 7pF Maximum |
| Equivalent Series Resistance | 40 Ohms Maximum |
| Mode of Operation | AT-Cut Fundamental |
| Drive Level | 1mWatt Maximum |
| Storage Temperature Range | -55°C to +125°C |
| Insulation Resistance | 500 Megaohms Minimum (Measured at 100Vdc) |

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

| | |
|------------------------------|---|
| ESD Susceptibility | MIL-STD-883, Method 3015, Class 1, HBM: 1500V |
| Fine Leak Test | MIL-STD-883, Method 1014, Condition A |
| Flammability | UL94-V0 |
| Gross Leak Test | MIL-STD-883, Method 1014, Condition C |
| Mechanical Shock | MIL-STD-202, Method 213, Condition C |
| Moisture Resistance | MIL-STD-883, Method 1004 |
| Moisture Sensitivity | J-STD-020, MSL1 |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K |
| Resistance to Solvents | MIL-STD-202, Method 215 |
| Solderability | MIL-STD-883, Method 2003 |
| Temperature Cycling | MIL-STD-883, Method 1010, Condition B |
| Vibration | MIL-STD-883, Method 2007, Condition A |

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MECHANICAL DIMENSIONS (all dimensions in millimeters)



| LINE | MARKING |
|------|--|
| 1 | E25.000M E=Ecliptek Designator |

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ± 0.1

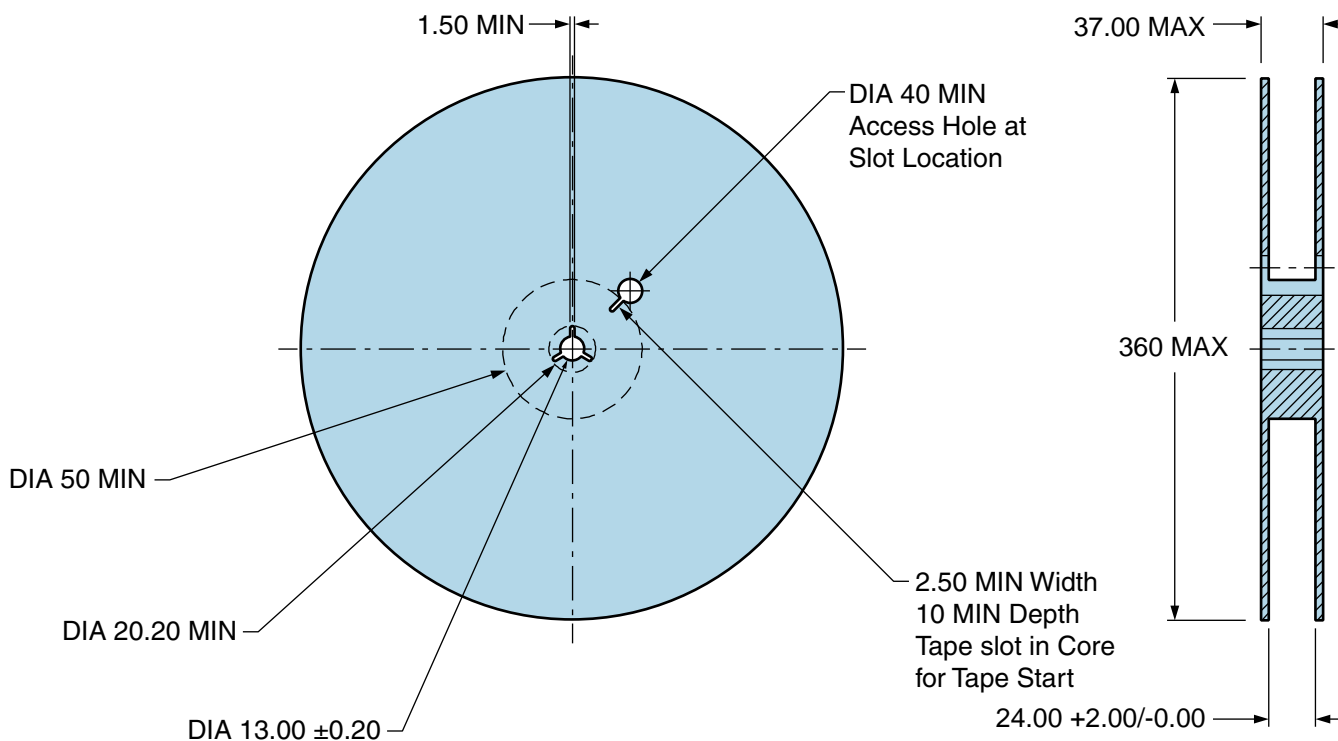
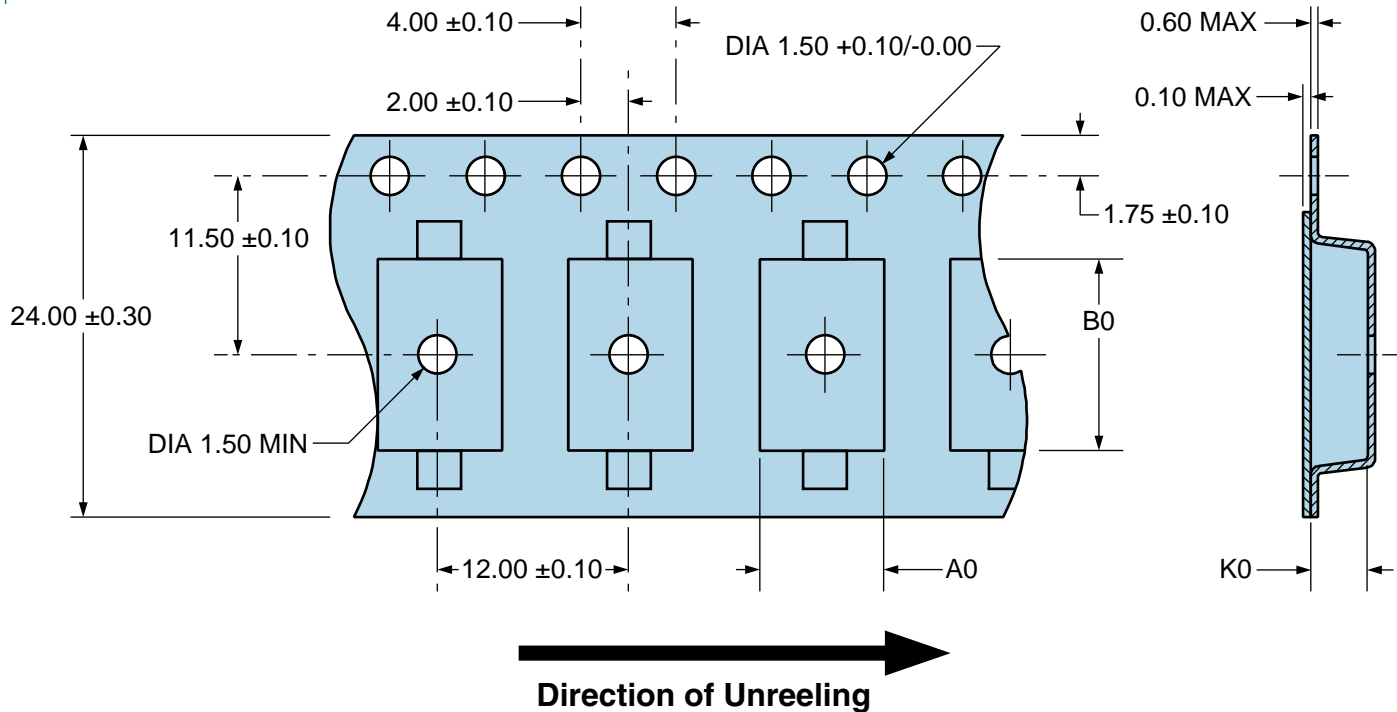
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Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

Compliant to EIA-481



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Recommended Solder Reflow Methods



High Temperature Infrared/Convection

| | |
|--|---|
| T_s MAX to T_L (Ramp-up Rate) | 3°C/Second Maximum |
| Preheat | |
| - Temperature Minimum (T_s MIN) | 150°C |
| - Temperature Typical (T_s TYP) | 175°C |
| - Temperature Maximum (T_s MAX) | 200°C |
| - Time (t_s MIN) | 60 - 180 Seconds |
| Ramp-up Rate (T_L to T_P) | 3°C/Second Maximum |
| Time Maintained Above: | |
| - Temperature (T_L) | 217°C |
| - Time (t_L) | 60 - 150 Seconds |
| Peak Temperature (T_P) | 260°C Maximum for 10 Seconds Maximum |
| Target Peak Temperature (T_P Target) | 250°C +0/-5°C |
| Time within 5°C of actual peak (t_p) | 20 - 40 Seconds |
| Ramp-down Rate | 6°C/Second Maximum |
| Time 25°C to Peak Temperature (t) | 8 Minutes Maximum |
| Moisture Sensitivity Level | Level 1 |
| Additional Notes | Temperatures shown are applied to body of device. |

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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 245°C

| | |
|--|--|
| Ts MAX to Tl (Ramp-up Rate) | 5°C/Second Maximum |
| Preheat | |
| - Temperature Minimum (Ts MIN) | N/A |
| - Temperature Typical (Ts TYP) | 150°C |
| - Temperature Maximum (Ts MAX) | N/A |
| - Time (ts MIN) | 30 - 60 Seconds |
| Ramp-up Rate (Tl to Tp) | 5°C/Second Maximum |
| Time Maintained Above: | |
| - Temperature (Tl) | 150°C |
| - Time (tL) | 200 Seconds Maximum |
| Peak Temperature (Tp) | 245°C Maximum |
| Target Peak Temperature (Tp Target) | 245°C Maximum 2 Times / 230°C Maximum 1 Time |
| Time within 5°C of actual peak (tp) | 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time |
| Ramp-down Rate | 5°C/Second Maximum |
| Time 25°C to Peak Temperature (t) | N/A |
| Moisture Sensitivity Level | Level 1 |
| Additional Notes | Temperatures shown are applied to body of device. |

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

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